76th Annual Meeting of Japan Laser Processing Society 5th Dec 2011

9:35 Opening Remark		Chair : KATAYAMA, Seiji (Osaka Univ.)			
	Plenary Session	Chair: KADOYA Teruyoshi (Laser Technology Fountain)			
9:40		Dr.Udo Klotgbach (Fraunhofer • Dresden (IWS))			
10:30		MIYAMOTO Isamu (Osaka Univ.)			
11:20		Haiyan ZHAO(Tsinghua Univ.)			
Lunch break (12:30~13:40)					

13:40 Short Presentation (Convention Hall) + Poster Presentation (Lobby)

Chairs: SAKAMOTO Haruhisa (Sophia Univ.), KAWAHITO Yousuke (Osaka Univ.)

There will be 22 poster presentations <<iin Japanese>> , poster exhibition as well as table-top catalogue exhibition.

Coffee break (15:20∼15:40)								
5A1 CFRP	Chair: TSUKAMOTO Masahiro (Osaka Univ.)		5B1 Advanced Laser Materials Processing and Laser System	Chair : NIINO Hiroyuki (AIST, PRI)				
15:40 [Specially-invited] Laser ablation of CFRP Composite Material by a Nanosecond Pulsed Laser and SM Fiber Laser	KUTSUNA muneharu (Advanced Laser Technology Research Center Co., Ltd.)	15:40	[Specially-invited] Progress in micro/nano stereolithography and 3-D molding techniques	MARUO shoji (Yokohama National Univ.)				
16:20 Cutting process of carbon fiber reinforced plastic plate using UV nanosecond laser	TSUKAMOTO masahiro (Osaka Univ.)	16:20	Femtosecond Laser Shock Processing of Solids	SANO tomokazu (Osaka Univ.)				
16:50 Short Pulse Laser Processing of CFRP	FUJITA masayuki (Institute for Laser Technology)	16:50	Application to laser processing of wavefront control technique using LCOS-SLM	ITOH haruyasu (Hamamatsu Photonics K.K.)				
17:20 Mechanical Behavior of Carbon Fiber Reinforced Plastics after laser cutting process	HARADA yoshihisa (AIST, PRI)		Quantitative Measurement of Adhesion Strength between Cell and Biointerface Model by Pulsed Laser-Induced Shock Wave.	YOSHIKAWA hiroshi (Saitama Univ.)				
17:50	7:50 Closing							
8:00 Beer and Snack break (Refectory 17:50~19:50) The Announcement of Poster Award and Best Author Award								

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	6A1 Solid-state laser mounted cutting machine	Chair : TAKENO Shozui (Mitsubishi Electric)		6B1 Laser processing for brittle or hard materials. (LED,SiC,etc.)	Chair FUKUMITSU, Kenshi (Hamamatsu Photonics K.K.)	
9:30	Trends in Cutting with Solid State Lasers	Florian Bartels (PRECITEC KG, Germany)	9:30	[Specially-invited] Laser micro machining to enhance the value of glass	IKENO junichi (Saitama Univ.)	
10:00	Report of High-end 3D-Laser trimming machine for the steel sheet of automobile	TUDA Kenichi (TRUMPF Corporation)	10:10	Micro-pattern processing technology, using ultra-short pulsed laser with higher-repetition.	FUKUYAMA satoshi (TOSHIBA MACHINE CO.,LTD.)	
10:30	Introduction of newly-developed cutting machine with 5kW multimode fiber laser	HAMADA Satoshi (Koike Sanso Kogyo Co., Ltd.)	10:40	Laser cutting process of brittleness materials by making use of a cooling nozzle	SUZUKI yoshiaki (Local Independent Administrative Institution the Tottori Institute of Industrial Technology)	
11:00	Solid-State Laser Processing System Development in Europe	TSUJI Masakazu (IPG Photonics Japan Limited)	11:10	Femtosecond Laser Solutions Are Powering a New Era of Precision Manufacturing	Michael M. Mielke (Raydiance, Inc.)	
	Lunch break (11:30~12:40)			Lunch break (11:40~12:40)		
	6A2 Latest laser processing in various products	Chair : ISHIDE Takashi (Mitsubishi Heavy Industries,Ltd)		6B2 Laser Aplications for FlexibleElectronics	Chair : MATSUSHITA Naohisa (Fuji Electric Co., Ltd.)	
	Development of 10kW fiber laser welding system and its applications	KITAGAWA akikazu (HITACHI ZOSEN CORPORATION)	12:40	[Specially-invited] Development of flexible devices and its fabrication techniques	HASEGAWA Tatsuo (AIST, PRI)	
13:10	Laser Welding of Light Poles	ISHIHARA koichi (Soutec Japan Co., Ltd.)	13:20	Flexible Solar Cells and Production Process using Laser Technology	TAKANO akihiro (Fuji Electric Co., Ltd.)	
13:40	Advantage of the short pulsed laser in processing ofabrittle material	SAKAMOTO tomoniri (LaserNet,INC.)	13:50	Laser Sintering Technology with Metal Nanoparticles for Electronics Packaging	MAEKAWA katsuhiro (Ibaraki Univ.)	
14:10	An attempt to enhance reaction rate for permeation induced nuclear transmutation by the laser irradiation	IWAMURA Yasuhiro (Mitsubishi Heavy Industries, ltd.)	14:20	Optics system of laser operation of flexible electronics manufacturing	KONDO kiyoyuki (Yuki engineering sytem.co.)	
14:40	New laser welding technology by beam shaping	MIURA Hideo (MIYACHI Corporation)				
Coffee break (15:10~15:30)				Coffee break (14:50~15:10)		
	6A3 Basic of Practical Welding	Chair : KITAGAWA, Akikazu (Hitachi Zosen)		6B3 Advanced Laser Processing for Solar-Cell Fabrication	Chair : WASHIO, Kunihiko (Paradigm Laser Research)	
15:30	Optical fiber delivery systems for high-power laser	ISHIDA tomohiko (MITSUBISHI CABLE INDUSTRIES, LTD.)	15:10	[Specially-invited] Laser Applications in Crystalline Silicon Solar Cell Production and Competing Technologies	Kyumin Lee (HYUNDAI HEAVY INDUSTRIES Co. Ltd., Korea)	
16:10	Performance Characteristic and Safety of Fiber, Lenses and Other Optical Parts for High Power Disk Laser	NAKAMURA tsuyoshi (TRUMPF Corporation)	15:50	Local Laser Doping into Silicon at Room Temprature and Application to Solar Cells	FUYUKI takashi (Nara Institute of Science and Technology)	
16:40	Optical system for high power laser material processing and applications	MIZUTANI shigeto (II-VI Japan Incorporated)	16:20	Laser Processing of Organic Photovoltaic Cells with a Roll-to-Roll Manufacturing Process	Wayne LEWIS (Beams Inc.)	
17:10	7:10 Closing		16:50	Laser processing for thin-film solar cells based on glass and plastic substates	FUKUDA naoaki (HITACHI ZOSEN CORPORATION)	
				Closing		